

# **CPW5-1700-Z050B**Silicon Carbide Schottky Diode Chip

Z-Rec<sup>tm</sup> Rectifier

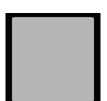
 $V_{ppm} = 1700 \text{ V}$ 

 $I_F = 50 A$ 

 $Q_c = 370 \text{ nC}$ 

## Features Chip Outline

- 1700-Volt Schottky Rectifier
- Zero Reverse Recovery
- Zero Reverse Recovery
  Zero Forward Recovery
- High-Frequency Operation
- Temperature-Independent Switching Behavior
- Extremely Fast Swtitching
- Positive Temperature Coefficient on V<sub>F</sub>



Part Number	Die Size	Anode	Cathode	
CPW5-1700-Z050B	6.0 x 6.0 mm <sup>2</sup>	Al	Ni/Ag	

# **Maximum Ratings**

Symbol	Parameter	Value	Unit	Test Conditions	Note
V <sub>RRM</sub>	Repetitive Peak Reverse Voltage	1700	V		
V <sub>RSM</sub>	Surge Peak Reverse Voltage	1700	V		
V <sub>R</sub>	DC Peak Blocking Voltage	1700	V		
I <sub>F</sub>	Maximum DC Current	50	А	T <sub>j</sub> =150°C	1
T <sub>J</sub> , T <sub>stg</sub>	Operating Junction and Storage Temperature	-55 to +175	°C		
T <sub>Proc</sub>	Maximum Procesing Temperature	325	°C	10 min Maximum	

#### Note:

1. Assumes  $\theta$ JC Thermal Resistance < 0.29 °C/W and  $T_c = 110$  °C



## **Electrical Characteristics**

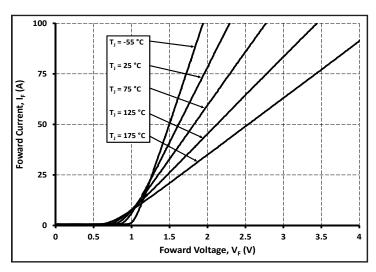
Symbol	Parameter	Тур.	Max.	Unit	Test Conditions	Note
V <sub>F</sub> DC Forward Voltage	DC Famuraud Valle are	1.6 1.3	1.9 1.4	V	$I_F = 50 \text{ A } T_J = 25^{\circ}\text{C}$ $I_F = 25 \text{ A } T_J = 25^{\circ}\text{C}$	Fig 1
	DC Forward Voltage	2.5 1.6	2.8 1.8	V	I <sub>F</sub> = 50 A T <sub>J</sub> =175°C I <sub>F</sub> = 25 A T <sub>J</sub> =175°C	
I <sub>R</sub> Reverse Current	avana Commant	120 <20	750 <75	μΑ	$V_R = 1700 \text{ V } T_J = 25^{\circ}\text{C}$ $V_R = 850 \text{ V } T_J = 25^{\circ}\text{C}$	Fig. 2
	Reverse Current	250 <40	1600 <105	μΑ	$V_R = 1700 \text{ V } T_J = 175^{\circ}\text{C}$ $V_R = 850 \text{ V } T_J = 175^{\circ}\text{C}$	Fig 2
Q <sub>c</sub>	Total Capacitive Charge	370		nC	V <sub>R</sub> = 1100 V, T <sub>J</sub> = 25°C	Fig 4
С	Total Capacitance	4240 240 234		pF	$V_R = 0 \text{ V, } T_J = 25^{\circ}\text{C, } f = 1 \text{ MHz}$ $V_R = 550 \text{ V, } T_J = 25^{\circ}\text{C, } f = 1 \text{ MHz}$ $V_R = 1100 \text{ V, } T_J = 25^{\circ}\text{C, } f = 1 \text{ MHz}$	Fig 3

## **Mechanical Parameters**

Parameter	Тур.	Unit
Die Size	6.0 × 6.0	mm
Anode Pad opening	4.4 x 4.4	mm
Thickness	380 ± 10%	μm
Wafer Size	100	mm
Anode Metalization (Al)	4	μm
Cathode Metalization (Ni/Ag) 1.8		μm
Frontside Passivation	Polyimide	



# **Typical Performance**



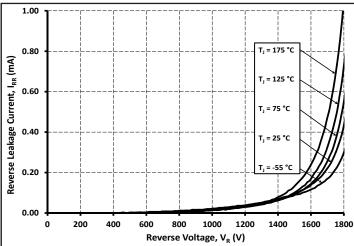


Figure 1. Typical Forward Characteristics

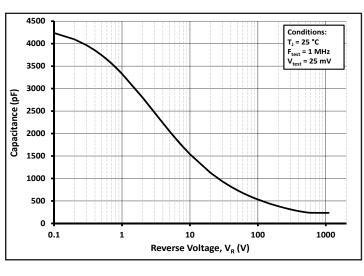


Figure 3. Typical Capacitance vs. Reverse Voltage

Figure 2. Typical Reverse Characteristics Conditions:

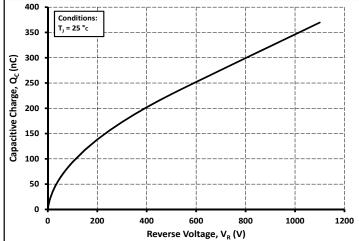
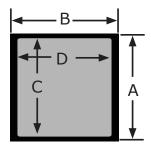


Figure 4. Typical Recovery Charge vs. Reverse Voltage



## **Chip Dimensions**



symbol	dimension			
	mm	inch		
Α	6.0	0.236		
В	6.0	0.236		
С	4.4	0.173		
D	4.4	0.173		

#### **Notes**

### RoHS Compliance

The levels of RoHS restricted materials in this product are below the maximum concentration values (also referred to as the threshold limits) permitted for such substances, or are used in an exempted application, in accordance with EU Directive 2011/65/EC (RoHS2), as implemented January 2, 2013. RoHS Declarations for this product can be obtained from your Cree representative or from the Product Documentation sections of www.cree.com.

#### REACh Compliance

REACh substances of high concern (SVHCs) information is available for this product. Since the European Chemical Agency (ECHA) has published notice of their intent to frequently revise the SVHC listing for the foreseeable future, please contact a Cree representative to insure you get the most up-to-date REACh SVHC Declaration. REACh banned substance information (REACh Article 67) is also available upon request.

• This product has not been designed or tested for use in, and is not intended for use in, applications implanted into the human body nor in applications in which failure of the product could lead to death, personal injury or property damage, including but not limited to equipment used in the operation of nuclear facilities, life-support machines, cardiac defibrillators or similar emergency medical equipment, aircraft navigation or communication or control systems, air traffic control systems, or weapons systems.

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